

DP-310050 (DEL01 P-474)

**ELECTRONIC MODULE**

Abstract of the Disclosure

An electronic module that includes a plurality of electrically conductive leads, an electrically conductive base plate, a first integrated circuit (IC) die, at least one material block and an electrically non-conductive overmold. The at least one material block functions to more closely match coefficient of thermal expansion (CTE) differences between components of the electronic module.